IQ-BOND 5132-CE

Flexibilized, Low-Stress, Electrically-Conductive, 1-Komponent Adhesive

Pre-Mixed, One Component, Solvent-Free, Hybrid-Epoxy Adhesive

Product Description:

IQ-BOND 5132-CE is a solvent-free, one-component, pre-mixed electrically-conductive adhesive, developed for applications where flexibility is required.

The rheology of IQ-BOND 5132-CE allows both dispensing, printing, as well as stamping processes. It has a high adhesion strength to substrate finishes commonly used in microelectronics applications.

IQ-BOND 5132-CE, in contrast to many other epoxy adhesives, is based on special selected flexibilized chemistry , making it an ideal solution for bonding applications of dissimilar materials with significant differences in CTE (coefficient of thermal expansion).

When fully cured, IQ-BOND 5132-CE is resistant to moisture, cleaning agents and dilute acids and bases. Its chemistry has been selected to combine flexibility with great adhesion, making it a preferred solution for bonding thermally mismatched substrates such as ceramic to aluminum, or ceramic to cupper.

The chemistry of IQ-BOND 5132-CE allows operation temperatures between -50°C and +200°C.

IQ-BOND 5132-CE is a solvent-free, 100% solids material and RoHS / REACH compliant.

For optimum curing performance, it's recommended to do the cure process in a conveyor belt oven. When curing IQ-BOND 5132-CE in a convection oven, it is recommended to apply a longer curing time for optimum adhesion properties.

For cleaning un-cured IQ-BOND 5132-CE from stencils, screens, squeegee, or other equipment, the use of IQ-CLEANER 9500 is recommended.

IQ-BOND 5132-CE is the electrically conductive version of IQ-BOND 2132.

Product Properties:

Appearance: Silver paste

Chemistry: Hybrid

Odor: Faint

Mix-Ratio: Not Applicable – pre-mixed "one component" adhesive





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• Fineness: < 40 μm

• Viscosity: ~ 160.000 mPa.s (CP52, RVII – at 25°C / 0,5 rpm)

Density ~ 3,1 gr/cc

Adhesion Strength: > 200 kg/cm²

Hardness: ~ 50 shore D / 95 shore A

Volume Resistivity: ~ 5 x 10⁻⁴ Ohm.cm (after cure 60 minutes 150°C)

% Ash residue: ~ 74 +/- 1

Thermal Conductivity: ~ 4,5 W/m.K

Cure Speed*:

15 minutes @ 175°C
60 minutes @ 150°C
90 minutes @ 120°C

For good mechanical strength, cure according above conditions is recommended. The final bond strength will depend on the residence time at the given cure temperature. Typically, a higher curing temperature, as well as a longer cure time will result in higher adhesion strength, and improved polymer crosslinking.

Processing parameters:

IQ-BOND 5132-CE is suitable for most dispensing systems. Prior to use, it's advised to let the adhesive IQ-BOND 5132-CE equilibrate to room temperature.

Storage stability:

When stored at temperatures below -20°C, in closed and sealed containers, the storage stability of IQ-BOND 5132-CE is 6 months from date of production. At temperatures < -40°C, the shelflife is 12 months.

At room temperature, IQ-BOND 5132-CE has a worklife / potlife of ~ 12 hours.

Attention:

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